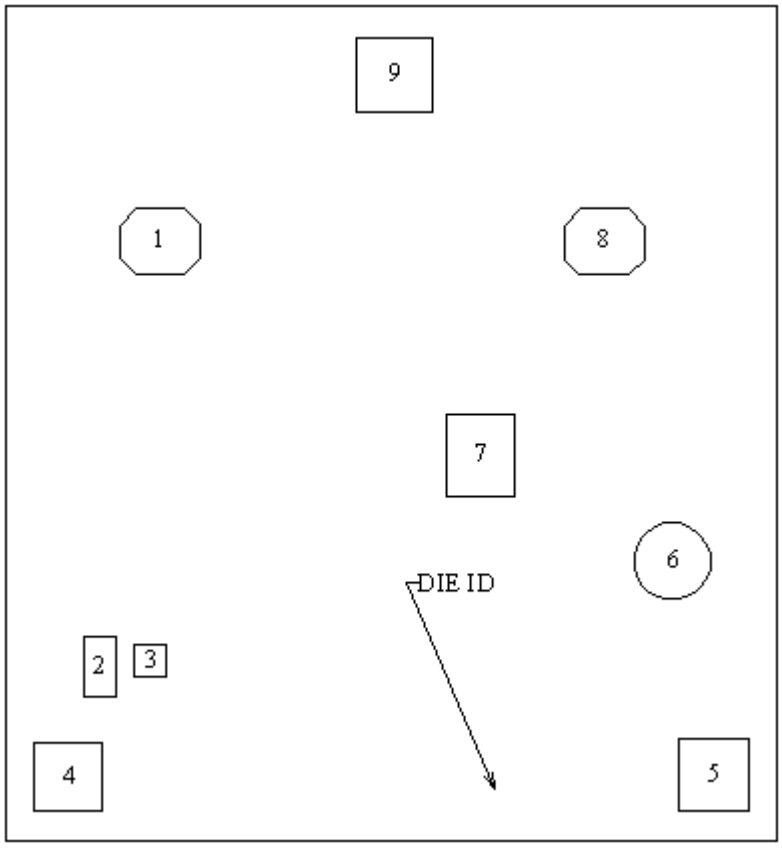
National Semiconductor
The Sight & Sound of Information

DPBU
Die Datasheet

LM117H MD8 MW8
3-TERMINAL ADJUSTABLE REGULATOR

March 12,2002

DIE LAYOUT (C-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	117C	Bond Pad Opening Size (min)	229µm x 188µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Gold
Die Size (Drawn)	2362µm x 2184µm 93mils x 86mils	Back Side Connection	OUTPUT
Thickness	254µm Nominal		
Min Pitch	146µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
OUTPUT	1	-655	516	229	x	188
NC	2	-827	-690	89	x	170
NC	3	-681	-673	91	x	91
OUTPUT	4	-914	-1001	193	x	198
ADJ	5	913	-997	196	x	206
NC	6	800	-391	208	x	208
INPUT	7	254	-91	193	x	234
OUTPUT	8	603	514	226	x	185
INPUT	9	10	987	213	x	211

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